

Title (en)  
Connector for leadless IC package

Title (de)  
Verbinder für leitungslose integrierte Schaltungspackung

Title (fr)  
Connecteur de circuit intégré sans fil

Publication  
**EP 0503810 B1 19960717 (EN)**

Application  
**EP 92301753 A 19920302**

Priority  
JP 7586491 A 19910315

Abstract (en)  
[origin: EP0503810A2] A connector for a leadless IC package having contacts to be pressure contacted conductive pads arranged on a lower surface of a leadless IC, wherein each of the contacts is formed of a spring element, the connector including a contact holding portion in which the spring element is implanted, a contact braking portion disposed above the contact holding portion, and a contact operating portion laterally movably disposed between the contact braking portion and the contact holding portion, the spring element being permitted to penetrate a contact operating through-hole formed in the operating portion, a distal end of the spring element being received in a contact braking through-hole formed in the braking portion, the spring element being sidewardly pressurized by an inner wall of the contact operating through-hole when the operating portion is moved in one direction, so that the spring element would be bent and displaced, the spring element being restored to its original state when the operating portion is laterally moved in the other direction, the distal end portion of the spring element being expanded and contracted while it is braked by the inner wall of the contact braking through-hole by the bending displacement and restoration, the distal end portion of the spring element being pressure contacted the conductive pad of the IC when the spring element is expanded. <IMAGE>

IPC 1-7  
**H05K 7/10**; **H01R 23/72**

IPC 8 full level  
**H01L 23/32** (2006.01); **H01R 11/18** (2006.01); **H01R 24/00** (2006.01); **H01R 33/76** (2006.01); **H05K 7/10** (2006.01); **G01R 1/073** (2006.01)

CPC (source: EP KR US)  
**H01R 9/00** (2013.01 - KR); **H01R 12/714** (2013.01 - EP US); **H05K 7/1069** (2013.01 - EP US); **G01R 1/07357** (2013.01 - EP US)

Cited by  
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Designated contracting state (EPC)  
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DOCDB simple family (publication)  
**EP 0503810 A2 19920916**; **EP 0503810 A3 19931208**; **EP 0503810 B1 19960717**; CA 2062199 A1 19920916; DE 69212189 D1 19960822; JP H05242935 A 19930921; JP H0675415 B2 19940921; KR 920019018 A 19921022; MY 108489 A 19960930; US 5320559 A 19940614

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